



Form 1449 (Modified) Information Disclosure Statement By Applicant (Use Several Sheets if Necessary)	Atty Docket No. NOVLP088/NVLS-2882 Applicant: Bandyopadhyay et al. Filing Date April 16, 2004	Application No.: 10/825,888 Group 2812
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U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub- class	Filing Date

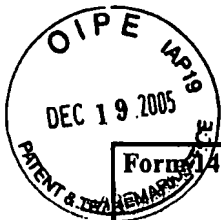
Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub- class	Translation	
							Yes	No

Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
JSKS	C1	U.S. Office Action mailed August 24, 2005, from U.S. Application No. 10/404,693 [Atty Dkt No. NOVLP064/NVLS-794].
JSKS	C2	U.S. Office Action mailed September 1, 2005, from U.S. Application No. 10/672,305 [Atty Dkt No. NOVLP069/NVLS-000821].
Examiner	Date Considered 5/4/07	

Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.



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JSKS	C1	Cho et al., "Method for Porogen Removal and Mechanical Strength Enhancement of Low-K Carbon Doped Silicon Oxide Using Low Thermal Budget Microwave Curing", U.S. Application No. 11/280,113, filed November 15, 2005 (Atty Dkt: NOVLP145/NVLS-3106)
Examiner	Date Considered 5/04/07	

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